



**Advanced Power
Electronics Corp.**

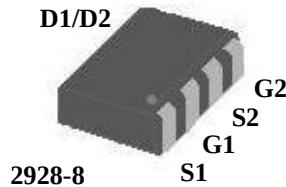
AP9938GEY-HF

Halogen-Free Product

DUAL N-CHANNEL ENHANCEMENT

MODE POWER MOSFET

- ▼ Capable of 1.8V Gate Drive
- ▼ Lower on-resistance
- ▼ Surface Mount Package
- ▼ RoHS Compliant & Halogen-Free

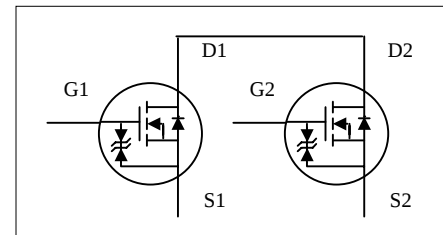


BV_{DSS}	20V
$R_{DS(ON)}$	16m Ω
I_D	7.5A

Description

Advanced Power MOSFETs utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The 2928-8 J-lead package provides good on-resistance performance and space saving like TSOP-6.



Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 8	V
$I_D@T_A=25^\circ\text{C}$	Drain Current ³ , V_{GS} @ 4.5V	7.5	A
$I_D@T_A=70^\circ\text{C}$	Drain Current ³ , V_{GS} @ 4.5V	6	A
I_{DM}	Pulsed Drain Current ¹	40	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	1.38	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	90	$^\circ\text{C}/\text{W}$



AP9938GEY-HF

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V, I _D =6A	-	12.6	16	mΩ
		V _{GS} =2.5V, I _D =4A	-	14.9	22	mΩ
		V _{GS} =1.8V, I _D =2A	-	18.5	26	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	0.3	-	1	V
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =6A	-	28	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V, V _{GS} =0V	-	-	10	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±8V, V _{DS} =0V	-	-	±30	uA
Q _g	Total Gate Charge	I _D =6A	-	16	26	nC
Q _{gs}	Gate-Source Charge	V _{DS} =10V	-	1.5	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	4	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =10V	-	7.5	-	ns
t _r	Rise Time	I _D =1A	-	14	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	31	-	ns
t _f	Fall Time	V _{GS} =5V	-	6	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	1075	1720	pF
C _{oss}	Output Capacitance	V _{DS} =10V	-	133	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	115	-	pF
R _g	Gate Resistance	f=1.0MHz	-	1.4	2.8	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =1.1A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =6A, V _{GS} =0V,	-	11	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	4	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤10sec ; 210 °C/W when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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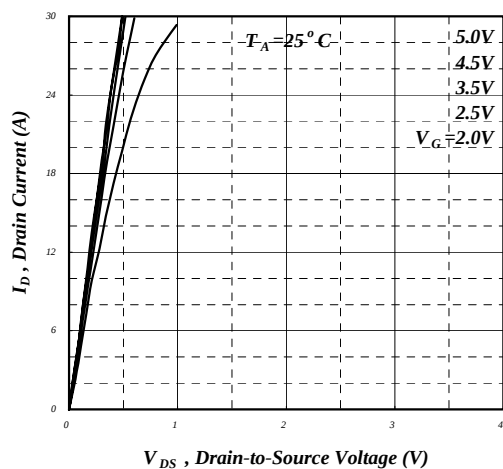


Fig 1. Typical Output Characteristics

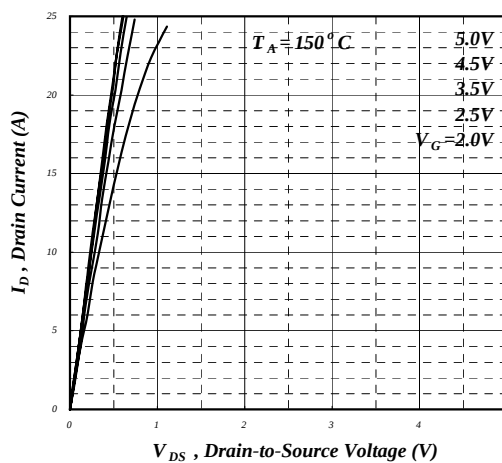


Fig 2. Typical Output Characteristics

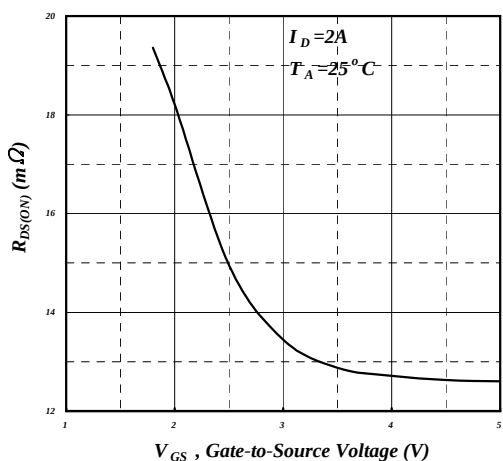


Fig 3. On-Resistance v.s. Gate Voltage

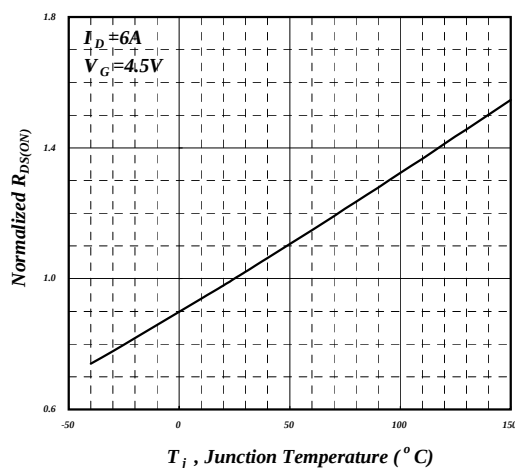


Fig 4. Normalized On-Resistance v.s. Junction Temperature

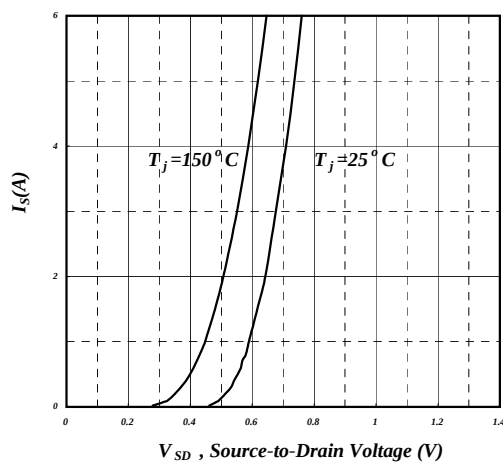


Fig 5. Forward Characteristic of Reverse Diode

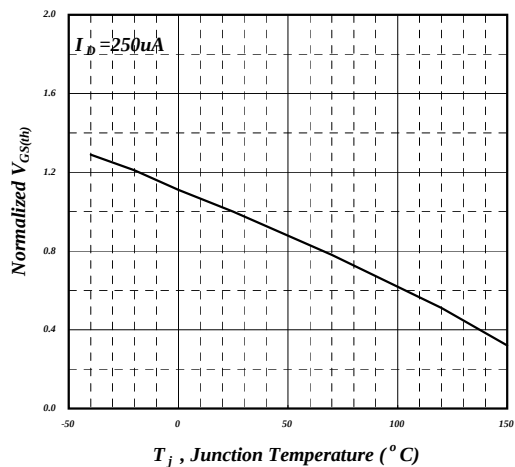
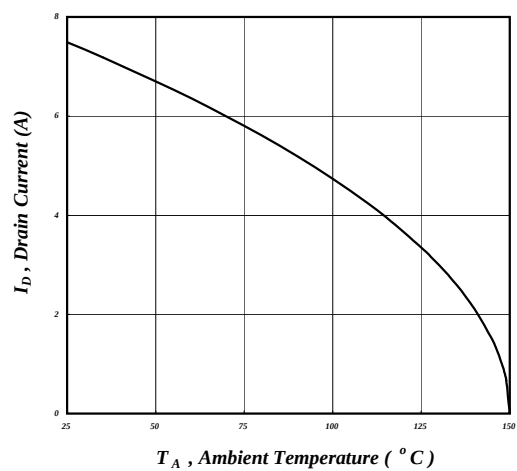
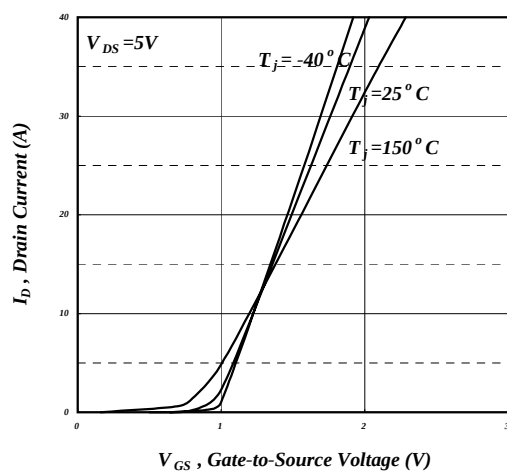
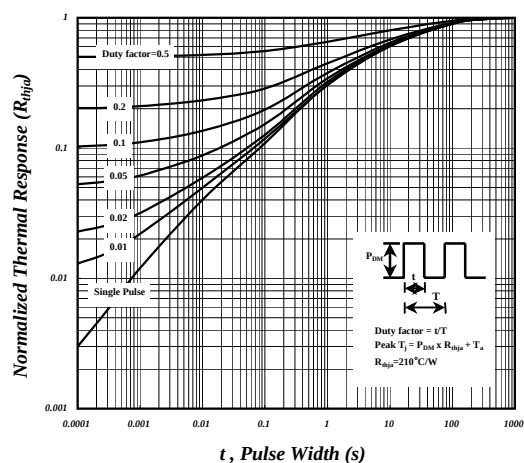
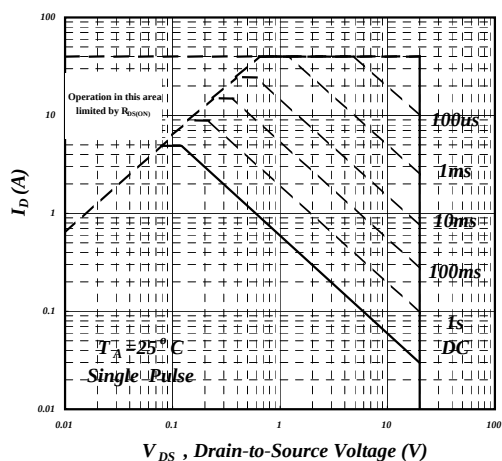
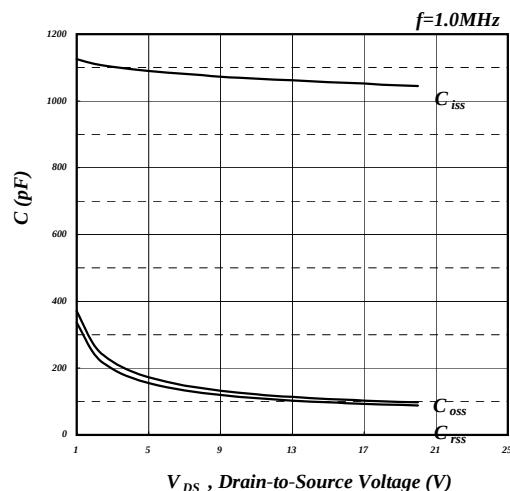
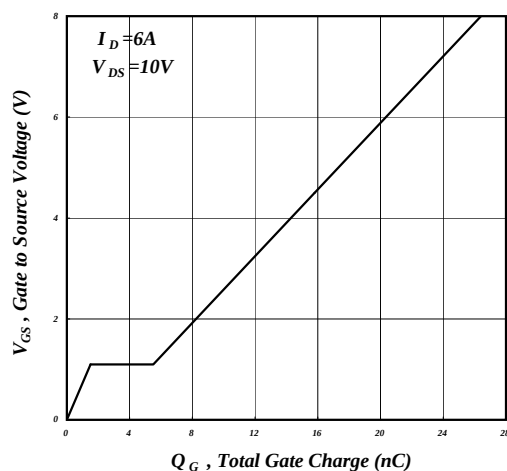


Fig 6. Gate Threshold Voltage v.s. Junction Temperature





MARKING INFORMATION

